

RELIABILITY REPORT  
FOR  
MAX256ASA+  
PLASTIC ENCAPSULATED DEVICES

November 15, 2010

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
SUNNYVALE, CA 94086

<b>Approved by</b>
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Quality Assurance
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## Conclusion

The MAX256ASA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX256 is an integrated primary-side controller and H-bridge driver for isolated power-supply circuits. The device contains an on-board oscillator, protection circuitry and internal FET drivers to provide up to 3W of power to the primary winding of a transformer. The MAX256 can be operated using the internal programmable oscillator or can be driven by an external clock for improved EMI performance. Regardless of the clock source being used, an internal flip-flop stage guarantees a fixed 50% duty cycle to prevent DC current flow in the transformer. The MAX256 operates from a single-supply voltage of +5V or +3.3V, and includes undervoltage lockout for controlled startup. The device prevents cross-conduction of the H-bridge MOSFETs by implementing break-before-make switching. Thermal shutdown circuitry provides additional protection against damage due to overtemperature conditions. The MAX256 is available in the 8-pin thermally-enhanced SO package. The device is specified for the automotive (-40°C to +125°C) temperature range.

**II. Manufacturing Information**

A. Description/Function:	3W Primary-Side Transformer H-Bridge Driver for Isolated Supplies
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines, Thailand
F. Date of Initial Production:	July 23, 2005

**III. Packaging Information**

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-1848
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	53°C/W
K. Single Layer Theta Jc:	7°C/W
L. Multi Layer Theta Ja:	43°C/W
M. Multi Layer Theta Jc:	7°C/W

**IV. Die Information**

A. Dimensions:	61 X 61 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)  
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 48 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 22.9 \times 10^{-9}$$

$\lambda = 22.9$  F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25C and 0.99 @ 55C (0.8 eV, 60% UCL)

### B. E.S.D. and Latch-Up Testing (lot TC0AAQ001G, D/C 0523)

The RU10 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX256ASA+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
<b>Static Life Test</b> (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0	TC0AAQ001G, DC 0523

Note 1: Life Test Data may represent plastic DIP qualification lots.